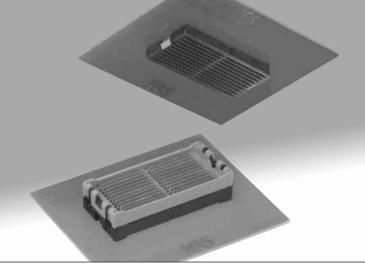
The product information in this catalog is for reference only. Please request the Engineering Drawing for the most current and accurate design information.

^{连接器网——汇勤电子旗下网站,}可站解决电气信号连接问题 High Speed, Parallel Board-to-Board Connector 380 contacts, Ball-Grid array termination

IT2 Series



Features

- **1. High-speed transmission** Differential impedance: 100Ω +/- 10% (Tr. 70 ps)
- 2. Contact reliability

Hirose's unique double contact point on each of the contacts assures highly reliable electrical and mechanical performance.

3. Self-alignment

Our unique 3-piece modular design together with large tolerances in the X and Y axis allows mating of several connectors mounted on the same PCB.

4. Low insertion / withdrawal forces

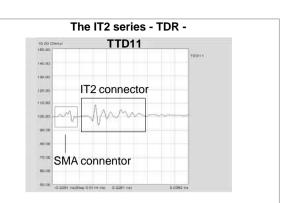
The unique contact configuration assures insertion force of 75 N max.

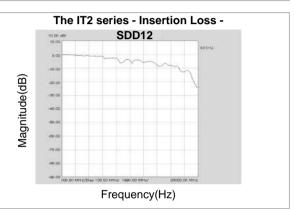
5. Customized Board-to-Board distance

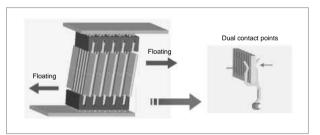
Transmission module can be designed to accommodate distance of 15 to 50 mm between parallel boards.

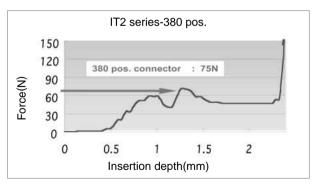
Applications

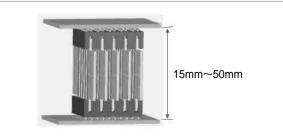
Routers, servers, base stations, communication equipment and other applications requiring high density and high speed connections between parallel boards.













■Production Specifications

	Current rating	0.5A	Operating temperature range	-55℃ to +85℃ (Note 1)	Storage temperature range	-10℃ to +60℃ (Note 2)
Ratings	Current voltage	50V AC	Operating humidity range	Relative humidity 95% (No condensation)	Storage humidity range	40% to 70% (Note 2)
Item	Specification		Conditions			
1. Insulation resistance	100 MΩ min.		100V DC			
2. Withstanding voltage	No flashover or insulation breakdown.		wn.	150V AC / one minute		
3. Contact resistance	50 mΩ max. (* Including conductor resistance.)		100 mA (Corresponding connector: IT2-380P-15H)			
4. Vibration	No electrical discontinuity of 1 μ s or more. No damage, cracks, or parts dislocation.		Frequency: 10 to 55 Hz, single amplitude of 0.75mm, 10 cycle in each of the 3 directions.			
5. Shock	No electrical discontinuity of 1 μ s. min. No damage, cracks, or parts dislocation.		Acceleration of 490 m/s ² , 11 ms duration, sine half-wave waveform, 3 cycles in each of the 3 axis			
6. Humidity	Contact resistance: 20 mΩ max.		96 hours at 40°C±2°C and humidity of 90% to 95%			
7. Temperature cycle	Insulation resistance: 100 M Ω min. No damage, cracks, or parts dislocation.		Temperature: $-55^{\circ}C \rightarrow +15^{\circ}C$ to $+35^{\circ}C \rightarrow +85^{\circ}C \rightarrow +15^{\circ}C$ to $+35^{\circ}C$ Duration: $30 \rightarrow 5$ max. $\rightarrow 30 \rightarrow 5$ max. (Minutes) 5 cycles			
8. Durability (insertion/ withdrawal)	Contact resistance: 20 mΩ max. Insulation resistance: 100 MΩ min. No damage, cracks, or parts dislocation.		20 cycles			
9. Resistance to soldering heat	No deformation of components affecting performance.		Reflow: At the recommended temperature profile (Peak temperature: 250°C max.) Detailed solder profile can be requested.			

Note1: Includes temperature rise caused by current flow.

Note2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating Temperature Range and Humidity range covers non- conducting condition of installed connectors in storage, shipment or during transportation.

Note3: Information contained in this catalog represents general requirements for this Series. Contact us for the drawings and specifications for a specific part number shown.

Materials/Finish

Receptacle

Part	Material	Finish	Remarks
Insulator	LCP	Color: Black	UL94V-0
Contacts	Phosphor bronze	Contact area: Gold plated	
Metal fitting	Phosphor bronze	Tin plated	

Transmission module

Part	Material	Finish	Remarks
Insulator	PBT	Color: Black/gray	UL94V-0
Board	FR-4	Contact area: Gold plated	

Note: Lead free products

Ordering information

Receptacles

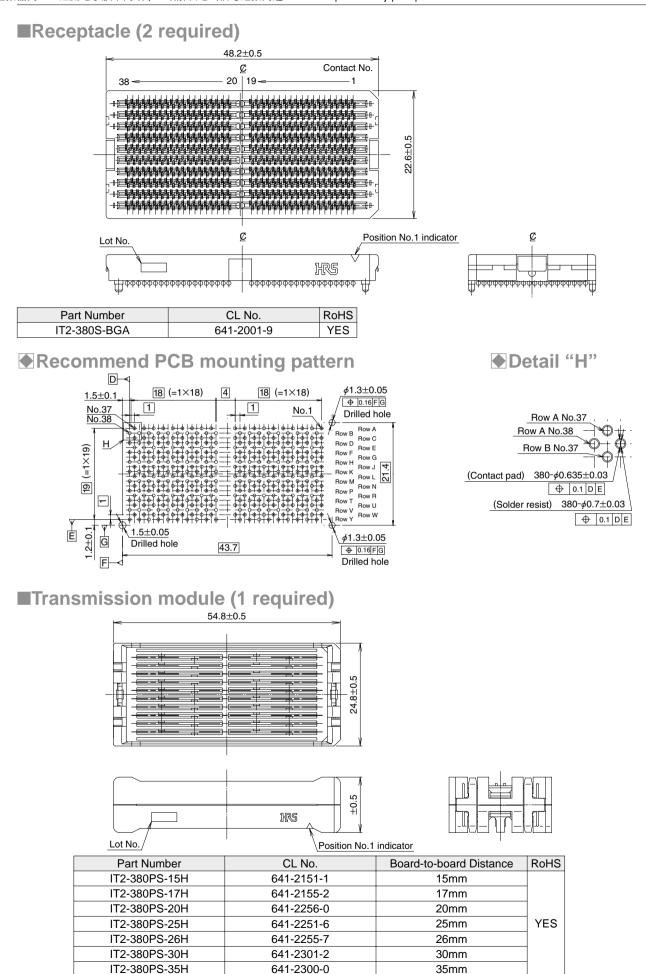


Transmission module

$$\frac{\text{IT2}}{\text{O}} - \frac{380}{\text{O}} + \frac{\text{P}}{\text{O}} + \frac{15\text{H}}{\text{O}}$$

 Series name 	: IT2
Number of contact	acts : 380
Connector	S : Receptacle
	P : Transmission module
BGA	
Ball grid allay (L	ead free)
6 Transmission	
S : Standard	
M : Customized	
6 Board to board	distance
15H : 15mm	26H : 26mm
17H : 17mm	30H : 30mm
20H : 20mm	35H : 35mm
25H : 25mm	

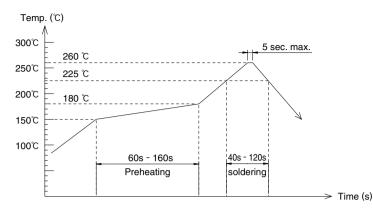
The product information in this catalog is for reference only. Please request the Engineering Drawing for the most current and accurate design information. 连接器网一一汇勤电子旗下网站, IT2 Spries, 出語, Speed, Parallel Board, to-Board (Stacking) Connector 380 contacts, Ball-Grid array termination nt D://www.Llgw.top/





Recommend Temperature Profile

●Using Lead-free Solder Paste



Solder composition: Paste, 96.5% Sn/3.0% Ag/0.5% Cu

Recomonded spacer Hight

The two parallel boards connected by the IT2 connectors should be fastened to additioal spacers between them.

Board-to-board Distance	Part Number	CL No.	Recomonded spacer Hight
15mm	IT2-380PS-15H	641-2151-1	15.35±0.05 mm
17mm	IT2-380PS-17H	641-2155-2	17.35±0.05 mm
20mm	IT2-380PS-20H	641-2256-0	20.35±0.05 mm
25mm	IT2-380PS-25H	641-2251-6	25.35±0.05 mm
26mm	IT2-380PS-26H	641-2255-7	26.35±0.05 mm
30mm	IT2-380PS-30H	641-2301-2	30.35±0.05 mm
35mm	IT2-380PS-35H	641-2300-0	35.35±0.05 mm

